Amendment to the Claims:

Please amend the claims as follows.

This listing of claims will replace all prior versions, and listing, of claims in the application:

Listing of Claims:

Claim 1 (previously presented): A biomolecular solder comprising a proteinaceous substance made a method comprising (a) providing a proteinaceous substance in a solvent; (b) denaturing the proteinaceous substance while moist with the solvent such that at least a portion of the proteinaceous substance bonds together and, (c) shaping the proteinaceous substance, wherein the solder is shaped before, during or after the denaturing of step (b), or a combination thereof, and, when shaped, the final shape of the solder is essentially maintained and the solubility of the proteinaceous substance is reduced in a physiological fluid at body temperature.

Claim 2 (previously presented): A solder according to claim 1 wherein the proteinaceous substance comprises a protein.

Claim 3 (previously presented): A solder according to claim 2 wherein the protein is any one of an albumin, an elastin, a fibrinogen, or any combination thereof.

Claim 4 (previously presented): A solder according to claim 1, further comprising a dye.

Claim 5 (previously presented): A solder according to claim 4 wherein the dye comprises an indocyanine green, a methylene blue or a fluorescein isothiocyanate.

Claim 6 (previously presented): A solder according to claim 1, further comprising an adjuvant.

Claim 7 (previously presented): A solder according to claim 6 wherein the adjuvant is selected from the group consisting of a growth factor, a sodium hyaluronate, a hormone and an anti-coagulant.

Claim 8 (previously presented): A solder according to claim 1 further comprising a material for improving the strength of the solder.

Claim 9 (previously presented): A solder according to claim 8 wherein the material comprises a polytetrafluoroethylene fibre or a ceramic fibre.

Claim 10 (previously presented): A kit comprising a solder according to any one of claims 1 to 9.

Claim 11 (previously presented): A method of preparing a biomolecular solder, the method comprising:

(a) providing a biomolecular solder comprising a proteinaceous substance and a solvent;

(b) shaping the solder into a desired shape, wherein the solder is shaped before, during or after the denaturing of step (c), or a combination thereof; and

(c) denaturing the proteinaceous substance while the solder is moist such that at least a portion of the proteinaceous substance bonds together and the desired shape of the solder is essentially maintained and the solubility of the proteinaceous substance is reduced in a physiological fluid at body temperature.

Claim 12 (previously presented): A method according to claim 11 wherein the proteinaceous substance is denatured by exposing the solder to energy for a time period that is sufficient to allow the energy to at least partially denature the proteinaceous substance.

Claim 13 (previously presented): A method according to claim 12 wherein the energy is thermal energy.

Claim 14 (previously presented): A method according to claim 11 wherein the proteinaceous substance is denatured by heating the solder at a temperature of greater than 40°C for a time period of about 30 seconds or longer.

Claim 15 (previously presented): A method according to claim 14 or 32 wherein the solder is heated in a hot liquid bath or in pressurized steam.

Claim 16 (previously presented): A method according to claim 11 wherein the proteinaceous substance is denatured by exposing the solder to a denaturing agent for a time period that is sufficient to allow the denaturing agent to denature the proteinaceous substance.

Claims 17 to 18 (canceled)

Claim 19 (previously presented): A method according to claim 11 wherein the solder further comprises a dye for improving energy deposition.

Claim 20 (previously presented): A method according to claim 19 wherein the dye is in an amount between 0.1 to 2.5% w/w of the solder.

Claim 21 (previously presented): A method according to claim 20 wherein the dye is mixed with the solvent, prior to mixing the solvent with the proteinaceous substance.

Claim 22 (previously presented): A method according to claim 11 further comprising drying the solder, wherein a majority of the solvent is removed from the solder during the drying of the solder.

Claim 23 (canceled)

Claim 24 (previously presented): A method according to claim 11 wherein the solder is applied to a support structure before the proteinaceous substance is denatured.

Claim 25 (previously presented): A method according to claim 24 wherein the support structure is a mesh, a stiffener or a graft material.

Claim 26 (previously presented): A method according to claim 11 further comprising the step of sterilizing the solder following the denaturing of the proteinaceous substance.

Claim 27 (previously presented): A method of welding biological tissue together, the method comprising:

(a) applying a solder according to claim 1 to the biological tissue to be welded together; and

(b) exposing the solder to an energy for a time sufficient to cause the solder to weld the biological tissue together.

Claim 28 (previously presented): A method according to claim 27 wherein the solder is moistened before application to the biological tissue.

Claim 29 (previously presented): A solder according to claim 1 wherein the proteinaceous substance is essentially insoluble in the physiological fluid at body temperature.

Claim 30 (previously presented): A solder according to claim 1 wherein the solder has been shaped from a composition comprising the proteinaceous substance in an amount of at least 40% w/w of the composition.

Claim 31 (previously presented): A solder according to claim 1 wherein the proteinaceous substance comprises a protein, a polypeptide, a mixture of proteins, a biodegradable protein, a fibrous material, a synthetic polypeptide or any combination thereof.

Claim 32 (previously presented): A method according to claim 11 further comprising drying the solder following the denaturation of the proteinaceous substance.

Claim 33 (previously presented): A method according to claim 11 wherein the solder, shaped into the predetermined shape, comprises the proteinaceous substance in an amount of at least 40% w/w or greater of the solder.

Claim 34 (previously presented): A method according to claim 11, wherein the solder comprises a proteinaceous substance in an amount in the range from 50% w/w to 80% w/w of the solder.

Claim 35 (previously presented): A method according to claim 33 or 34 wherein the solder comprises a solvent in an amount up to 60% w/w/ of the solder.

Claim 36 (previously presented): A method according to claim 14 wherein the solder is heated at a temperature in a range from 75°C to 100°C.

Claim 37 (previously presented): A method according to claim 36 wherein the solder is heated at a temperature in a range from 100°C to 150°C.

Claim 38 (previously presented): A method according to claim 16 wherein the denaturing agent comprises a chemical.

Claim 39 (previously presented): A method according to any one of claims 11, 32, or 33 wherein the proteinaceous substance comprises a protein, a polypeptide, a mixture of proteins, a biodegradable protein, a fibrous material, a synthetic polypeptide or any combination thereof.

Claim 40 (previously presented): A method according to claim 39 wherein the proteinaceous substance comprises at least one substance selected from the group consisting of a protein and a polypeptide.

Claim 41 (previously presented): A method according to claim 40 wherein the proteinaceous substance comprises at least one protein selected from the group consisting of an albumin, an elastin, and a fibrinogen.

Claim 42 (previously presented): A method according to claim 28 wherein the moistening of the solder increases flexibility of the solder.

Claim 43 (previously presented): The biomolecular solder of claim 1, wherein the solvent comprises an aqueous solvent.

Claim 44 (previously presented): The biomolecular solder of claim 43, wherein the aqueous solvent comprises water or saline.

Claim 45 (previously presented): The method of claim 11, wherein the solvent comprises an aqueous solvent.

Claim 46 (previously presented): The method of claim 45, wherein the aqueous solvent comprises water or saline.

Claim 47 (previously presented): The method of claim 11, wherein the proteinaceous substance is denatured by exposing the solder to a laser energy.

Claim 48 (previously presented): The method of claim 47, wherein the laser is a diode laser.

Claim 49 (previously presented): The method of claim 27, wherein the biological tissue is welded together to effect a repair.

Claim 50 (previously presented): The biomolecular solder of claim 1, wherein all of the proteinaceous substance is denatured.

Claim 51 (previously presented): The biomolecular solder of claim 1, wherein a portion of the proteinaceous substance is denatured.

Claim 52 (previously presented): The method of claim 11, wherein all of the proteinaceous substance is denatured.

Claim 53 (previously presented): The method of claim 11, wherein a portion of the proteinaceous substance is denatured.

Claim 54 (previously presented): The biomolecular solder of claim 1, wherein the method of making the solder further comprises sterilizing the biomolecular solder.

Claim 55 (previously presented): The biomolecular solder of claim 1, wherein the proteinaceous substance is shaped into a sheet, a tube, a partial tube or a rod.

Claim 56 (previously presented): The method of claim 11, the desired shape comprises a sheet, a tube, a partial tube or a rod.

Claim 57 (new): A biomolecular solder comprising a proteinaceous substance that has been at least partially denatured while moist such that the proteinaceous substance bonds together and, when shaped, the shape of the solder is thereby essentially maintained and the solubility of the proteinaceous substance is reduced in a physiological fluid at body temperature.

Claim 58 (new): The biomolecular solder of claim 57, wherein the solder is shaped before denaturation.

Claim 59 (new): The biomolecular solder of claim 57, wherein the solder is shaped after denaturation.

Claim 60 (new): The biomolecular solder of claim 57, wherein the proteinaceous substance comprises a protein.

Claim 61 (new): The biomolecular solder of claim 60, wherein the protein comprises an albumin, an elastin, a fibrinogen, or any combination thereof.

Claim 62 (new): The biomolecular solder of claim 57, further comprising a dye for improving energy deposition into the solder when the solder is exposed to energy.

Claim 63 (new): The biomolecular solder of claim 57, wherein the proteinaceous substance has been at least partially denatured while moist with a solvent.

Claim 64 (new): The biomolecular solder of claim 63, wherein the solvent comprises an aqueous solvent.

Claim 65 (new): The biomolecular solder of claim 64, wherein the aqueous solvent comprises water or saline.